

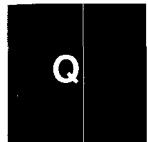
Session Q:

Microwave Packaging and Manufacturing

Chairman: Douglas Maki

M/A-COM
Lowell, MA

This session's papers cover a broad range of packaging and manufacturing issues from modeling through testing and yield analysis. The session begins with a novel approach to thermal management through phase change mechanisms from AEL followed by papers on resonant field measurements on microwave housings and a low cost method of injection molding complex packages. A statistical approach to test strategy is presented by TRW that can significantly reduce the overall cost of MMICs. Finally, a paper from Pacific Monolithics describes the performance and yield of a 5-bit X-band phase shifter gathered from measurements on thousands of circuits.



Q

3:30 p.m.-5:00 p.m., Tuesday, May 8, 1990
W101